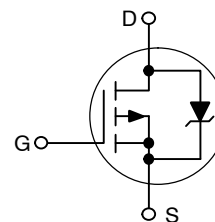


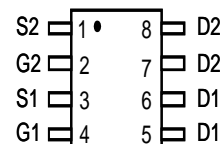
Features

- High Efficiency Components in a Dual SOP-8 Package
- High Density Power MOSFET with Low $R_{DS(on)}$
- Miniature SOP-8 Surface Mount Package – Saves Board Space
- Diode Exhibits High Speed with Soft Recovery
- I_{DSS} Specified at Elevated Temperature
- Avalanche Energy Specified



Applications

- DC-DC Converters
- Low Voltage Motor Control
- Power Management in Portable and Battery-Powered Products, i.e.: Computers, Printers, PCMCIA Cards, Cellular & Cordless Telephones
- $V_{DS(V)} = -30V$
- $R_{DS(ON)} < 85m\Omega$ ($V_{GS} = -10V$)
- $R_{DS(ON)} < 125m\Omega$ ($V_{GS} = -4.5V$)



MAXIMUM RATINGS ($T_J = 25^\circ C$ unless otherwise noted)

Rating	Symbol	Value	Unit
Drain-to-Source Voltage	V_{DSS}	-30	V
Gate-to-Source Voltage – Continuous	V_{GS}	± 20	V
Thermal Resistance – Junction-to-Ambient (Note 1) Total Power Dissipation @ $T_A = 25^\circ C$ Continuous Drain Current @ $25^\circ C$ Continuous Drain Current @ $70^\circ C$ Pulsed Drain Current (Note 4)	$R_{\theta JA}$ P_D I_D I_D I_{DM}	171 0.73 -2.34 -1.87 -8.0	$^\circ C/W$ W A A A
Thermal Resistance – Junction-to-Ambient (Note 2) Total Power Dissipation @ $T_A = 25^\circ C$ Continuous Drain Current @ $25^\circ C$ Continuous Drain Current @ $70^\circ C$ Pulsed Drain Current (Note 4)	$R_{\theta JA}$ P_D I_D I_D I_{DM}	100 1.25 -3.05 -2.44 -12	$^\circ C/W$ W A A A
Thermal Resistance – Junction-to-Ambient (Note 3) Total Power Dissipation @ $T_A = 25^\circ C$ Continuous Drain Current @ $25^\circ C$ Continuous Drain Current @ $70^\circ C$ Pulsed Drain Current (Note 4)	$R_{\theta JA}$ P_D I_D I_D I_{DM}	62.5 2.0 -3.86 -3.1 -15	$^\circ C/W$ W A A A
Operating and Storage Temperature Range	T_J, T_{stg}	-55 to +150	$^\circ C$
Single Pulse Drain-to-Source Avalanche Energy – Starting $T_J = 25^\circ C$ ($V_{DD} = -30$ Vdc, $V_{GS} = -4.5$ Vdc, Peak I_L = -7.5 Apk, L = 5 mH, $R_G = 25 \Omega$)	E_{AS}	140	mJ
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	T_L	260	$^\circ C$

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted) (Note 5)

Characteristic	Symbol	Min	Typ	Max	Unit	
Drain-to-Source Breakdown Voltage ($V_{GS} = 0\text{ Vdc}$, $I_D = -250\ \mu\text{Adc}$) Temperature Coefficient (Positive)	$V_{(BR)DSS}$	-30	-30		Vdc mV/ $^\circ\text{C}$	
Zero Gate Voltage Drain Current ($V_{DS} = -24\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$, $T_J = 25^\circ\text{C}$) ($V_{DS} = -24\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$, $T_J = 125^\circ\text{C}$) ($V_{DS} = -30\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$, $T_J = 25^\circ\text{C}$)	I_{DSS}			-1.0 -20 -2.0	μAdc	
Gate-Body Leakage Current ($V_{GS} = -20\text{ Vdc}$, $V_{DS} = 0\text{ Vdc}$)	I_{GSS}			-100	nAdc	
Gate-Body Leakage Current ($V_{GS} = +20\text{ Vdc}$, $V_{DS} = 0\text{ Vdc}$)	I_{GSS}			100	nAdc	
Gate Threshold Voltage ($V_{DS} = V_{GS}$, $I_D = -250\ \mu\text{Adc}$) Temperature Coefficient (Negative)	$V_{GS(th)}$	-1.0	-1.7 3.6	-2.5	Vdc	
Static Drain-to-Source On-State Resistance ($V_{GS} = -10\text{ Vdc}$, $I_D = -3.05\text{ Adc}$) ($V_{GS} = -4.5\text{ Vdc}$, $I_D = -1.5\text{ Adc}$)	$R_{DS(on)}$		0.063 0.090	0.085 0.125	Ω	
Forward Transconductance ($V_{DS} = -15\text{ Vdc}$, $I_D = -3.05\text{ Adc}$)	g_{FS}		5.0		Mhos	
Input Capacitance	$(V_{DS} = -24\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$, $f = 1.0\text{ MHz}$)		C_{iss}	520	750	pF
Output Capacitance			C_{oss}	170	325	
Reverse Transfer Capacitance			C_{rss}	70	135	
Turn-On Delay Time	$(V_{DD} = -24\text{ Vdc}$, $I_D = -3.05\text{ Adc}$, $V_{GS} = -10\text{ Vdc}$, $R_G = 6.0\ \Omega$)		$t_{d(on)}$	12	22	ns
Rise Time			t_r	16	30	
Turn-Off Delay Time			$t_{d(off)}$	45	80	
Fall Time			t_f	45	80	
Turn-On Delay Time	$(V_{DD} = -24\text{ Vdc}$, $I_D = -1.5\text{ Adc}$, $V_{GS} = -4.5\text{ Vdc}$, $R_G = 6.0\ \Omega$)		$t_{d(on)}$	16		ns
Rise Time			t_r	42		
Turn-Off Delay Time			$t_{d(off)}$	32		
Fall Time			t_f	35		
Total Gate Charge	$(V_{DS} = -24\text{ Vdc}$, $V_{GS} = -10\text{ Vdc}$, $I_D = -3.05\text{ Adc}$)		Q_{tot}	16	25	nC
Gate-Source Charge			Q_{gs}	2.0		
Gate-Drain Charge			Q_{gd}	4.5		
Diode Forward On-Voltage ($I_S = -3.05\text{ Adc}$, $V_{GS} = 0\text{ V}$) ($I_S = -3.05\text{ Adc}$, $V_{GS} = 0\text{ V}$, $T_J = 125^\circ\text{C}$)	V_{SD}		-0.96 -0.78	-1.25	Vdc	
Reverse Recovery Time	$(I_S = -3.05\text{ Adc}$, $V_{GS} = 0\text{ Vdc}$, $dI_S/dt = 100\text{ A}/\mu\text{s}$)		t_{rr}	34		ns
			t_a	18		
			t_b	16		
Reverse Recovery Stored Charge	Q_{RR}		0.03		μC	

5. Handling precautions to protect against electrostatic discharge is mandatory.
6. Indicates Pulse Test: Pulse Width = 300 μs max, Duty Cycle = 2%.
7. Switching characteristics are independent of operating junction temperature.

TYPICAL ELECTRICAL CHARACTERISTICS

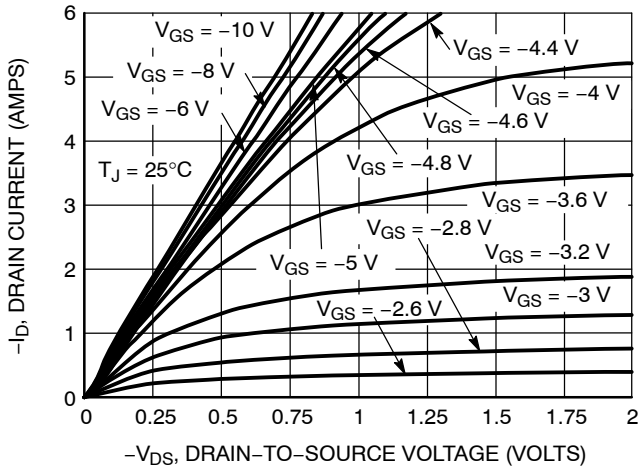


Figure 1. On-Region Characteristics

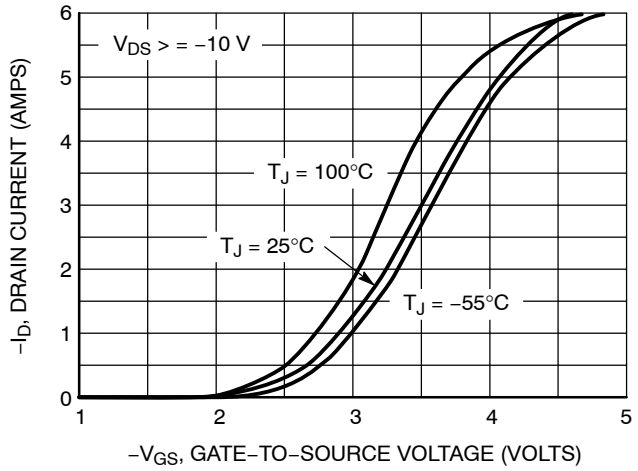


Figure 2. Transfer Characteristics

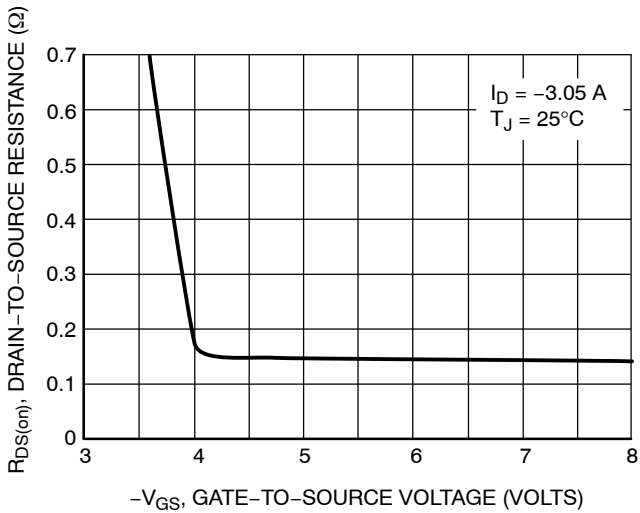


Figure 3. On-Resistance vs. Gate-to-Source Voltage

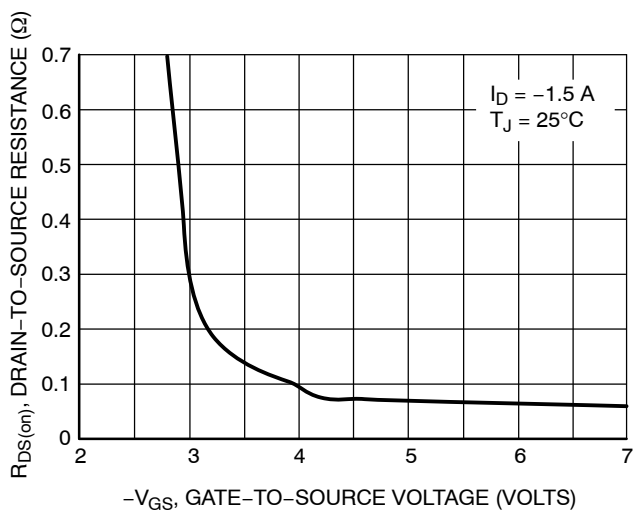


Figure 4. On-Resistance vs. Gate-to-Source Voltage

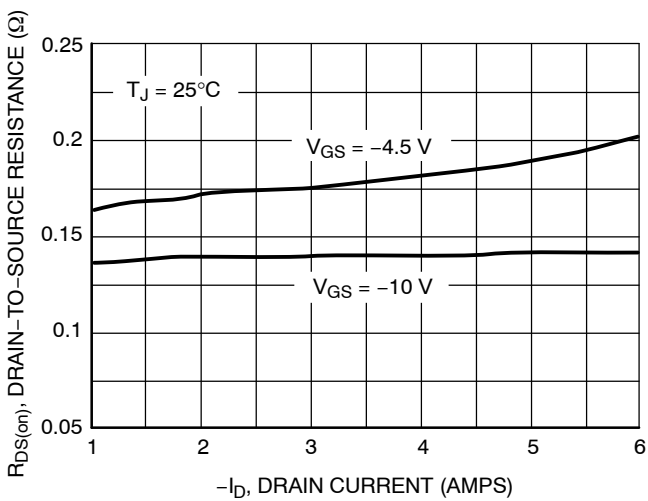


Figure 5. On-Resistance vs. Drain Current and Gate Voltage

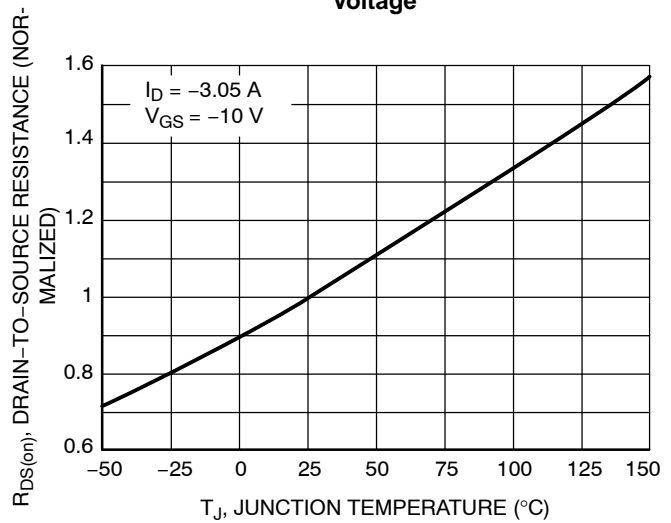


Figure 6. On Resistance Variation with Temperature

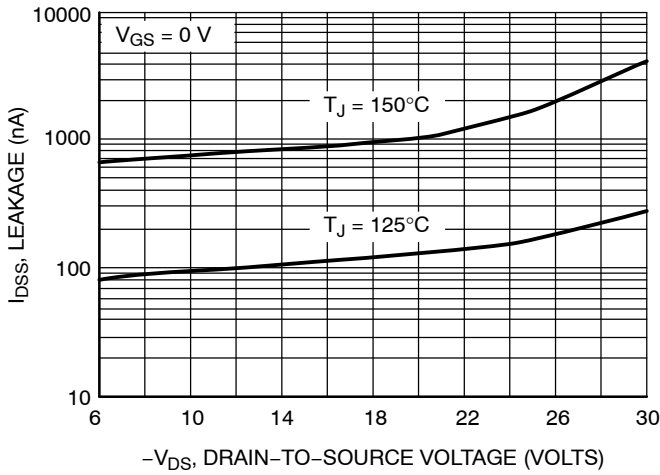


Figure 7. Drain-to-Source Leakage Current vs. Voltage

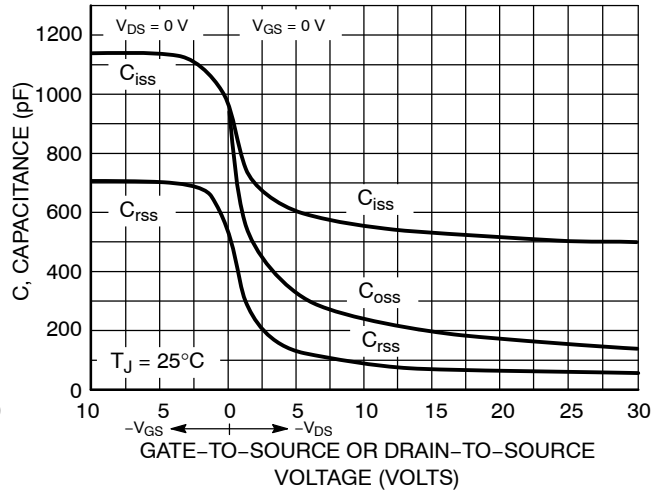


Figure 8. Capacitance Variation

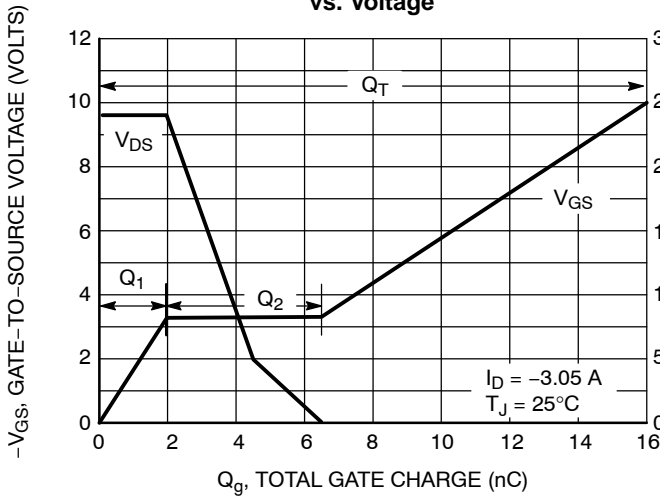


Figure 9. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

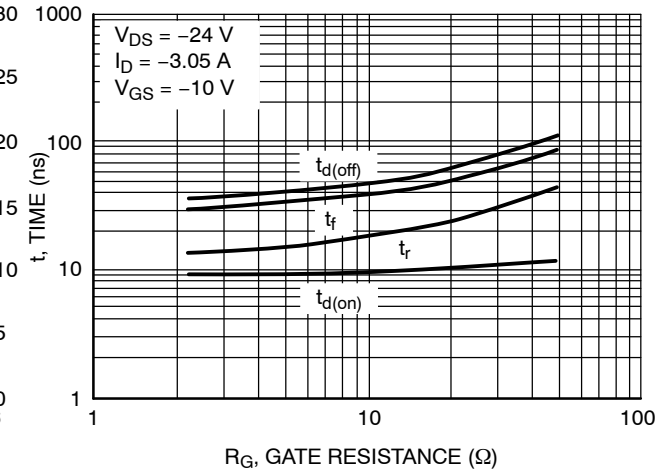


Figure 10. Resistive Switching Time Variation vs. Gate Resistance

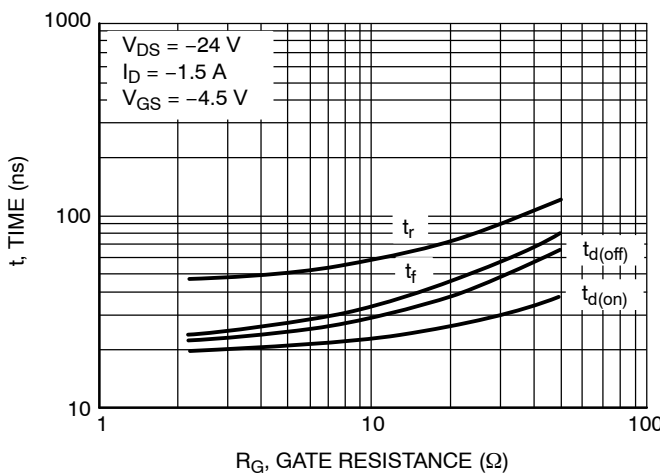


Figure 11. Resistive Switching Time Variation vs. Gate Resistance

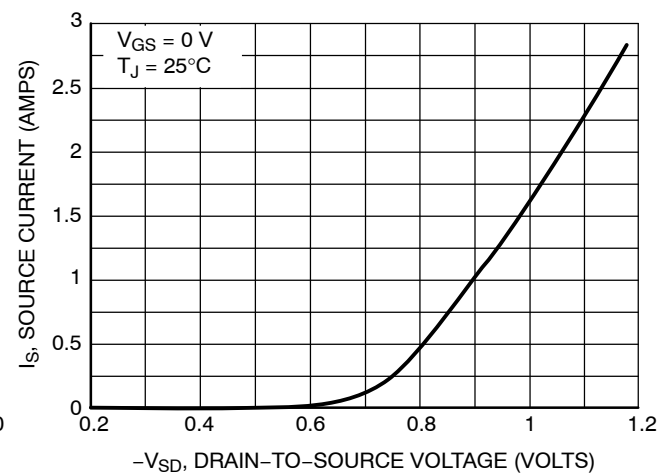


Figure 12. Diode Forward Voltage vs. Current

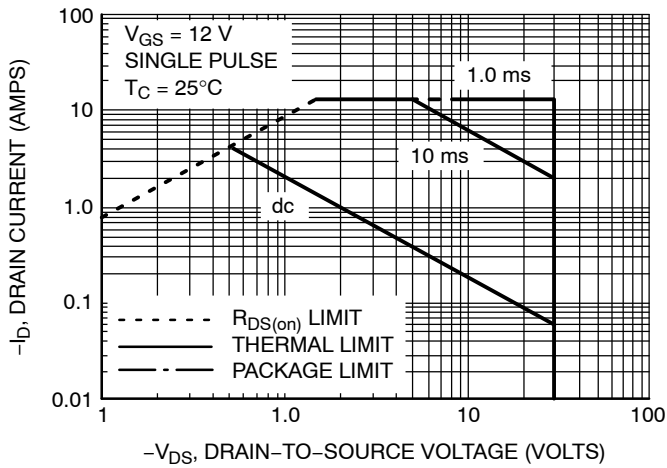


Figure 13. Maximum Rated Forward Biased Safe Operating Area

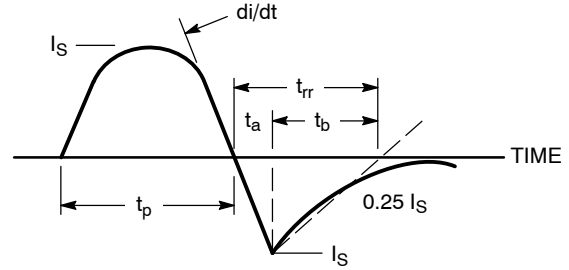


Figure 14. Diode Reverse Recovery Waveform

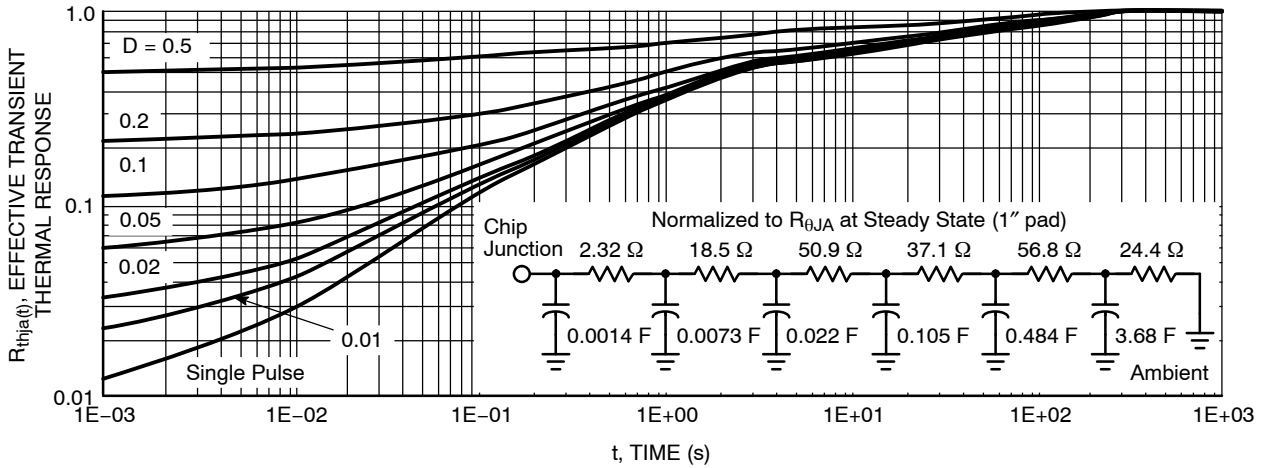
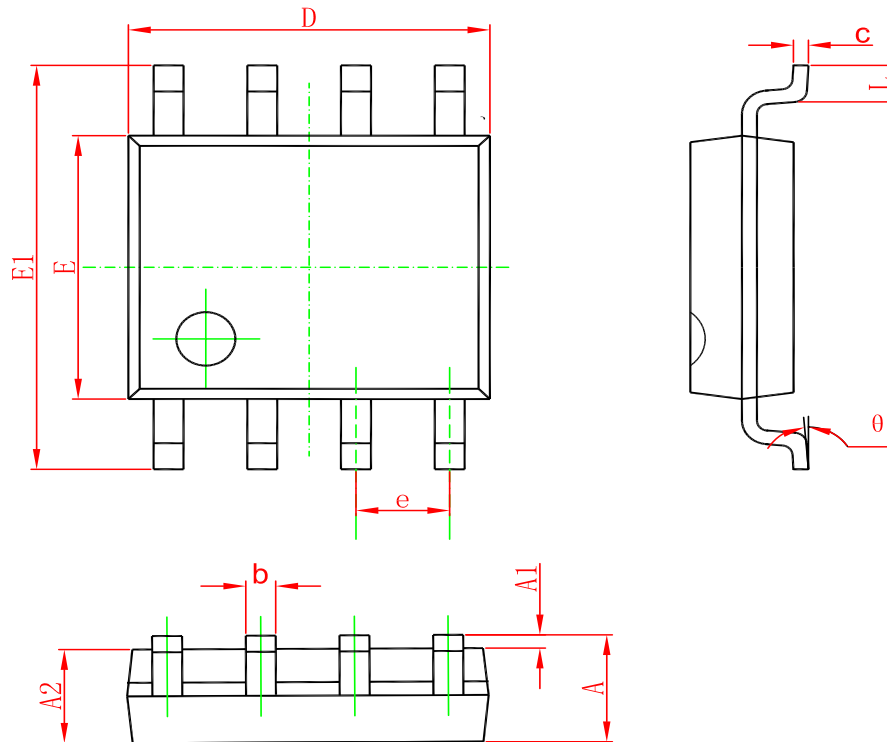


Figure 15. FET Thermal Response

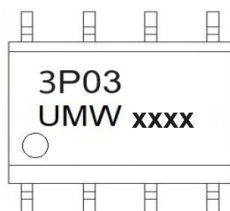
PACKAGE OUTLINE DIMENSIONS

SOP-8



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

Marking



Ordering information

Order code	Package	Baseqty	Deliverymode
UMW NTMD3P03R2G	SOP-8	3000	Tape and reel

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for [MOSFET](#) category:

Click to view products by [Youtai](#) manufacturer:

Other Similar products are found below :

[IRFD120](#) [JANTX2N5237](#) [2SK2267\(Q\)](#) [BUK455-60A/B](#) [TK100A10N1,S4X\(S](#) [MIC4420CM-TR](#) [VN1206L](#) [NDP4060](#) [SI4482DY](#)
[IRS2092STRPBF-EL](#) [IPS70R2K0CEAKMA1](#) [TK31J60W5,S1VQ\(O](#) [TK31J60W,S1VQ\(O](#) [TK16J60W,S1VQ\(O](#) [2SK2614\(TE16L1,Q\)](#)
[DMN1017UCP3-7](#) [EFC2J004NUZTDG](#) [P85W28HP2F-7071](#) [DMN1053UCP4-7](#) [NTE2384](#) [DMC2700UDMQ-7](#) [DMN2080UCB4-7](#)
[DMN61D9UWQ-13](#) [US6M2GTR](#) [DMN31D5UDJ-7](#) [DMP22D4UFO-7B](#) [IPS60R3K4CEAKMA1](#) [DMN1006UCA6-7](#) [DMN16M9UCA6-7](#)
[STF5N65M6](#) [IRF40H233XTMA1](#) [STU5N65M6](#) [DMN6022SSD-13](#) [DMN13M9UCA6-7](#) [DMTH10H4M6SPS-13](#) [IPS60R360PFD7SAKMA1](#)
[DMN2990UFB-7B](#) [SSM3K35CT,L3F](#) [IPLK60R1K0PFD7ATMA1](#) [2N7002W-G](#) [MCAC30N06Y-TP](#) [IPWS65R035CFD7AXKSA1](#)
[MCQ7328-TP](#) [SSM3J143TU,LXHF](#) [DMN12M3UCA6-7](#) [PJMF280N65E1_T0_00201](#) [PJMF380N65E1_T0_00201](#)
[PJMF280N60E1_T0_00201](#) [PJMF600N65E1_T0_00201](#) [PJMF900N65E1_T0_00201](#)